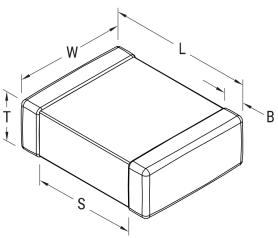


C1206X362G3HAL7210

SMD Comm X8R HT150C Flex, Ceramic, 3600 pF, 2%, 25 VDC, X8R, SMD, MLCC, High Temperature, Ultra-Stable, 1206



Click here for the 3D model.

Dimensions	
Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
Т	0.9mm +/-0.20mm
S	1.5mm MIN
В	0.6mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

General Information	
Series	SMD Comm X8R HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	Ultra-Stable
RoHS	No
Prop 65	▲ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov.
Termination	Flexible Termination With Lead (SnPb)
Marking	false
AEC-Q200	No
Typical Component Weight	25 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	3600 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	2%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+150°C
Temperature Coefficient	X8R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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